

OVERVIEW



1. Power connector	8. Power button
2. HDMI (for i3) / DisplayPort (for i5)	9. Serial
3. USB 3.2 Gen 2	10. Serial
4. Thunderbolt 4	11. USB-C 3.2 Gen 2
5. Ethernet (RJ-45)	12. USB 3.2 Gen 2
6. Ethernet (RJ-45)	13. USB 3.2 Gen 2
7. Kensington Security Slot	14. Headphone / microphone combo jack (3.5mm)

PERFORMANCE

Processor

Processor Family

11th Generation Intel® Core™ i3 / i5 Processor

Processor**[1]

Processor Name	Cores	Threads	Base Frequency	Cache	Memory Support	Processor Graphics
Core i3-1115GRE	2	4	1.7GHz	6MB	DDR4-3200	Intel UHD Graphics
Core i5-1145GRE	4	8	1.1GHz	8MB	DDR4-3200	Intel Iris® Xe Graphics

Notes:

1. Intel Turbo Boost is disabled on SE30. The maximum TDP of CPU is 12W. The max frequency is not obtainable at high work levels, the CPU will adjust the frequency to obtain the maximum TDP allowed.

Operating System

Operating System**

- Windows® 10 IoT Enterprise LTSC 2021
- Ubuntu Core
- Ubuntu Server
- No operating system

Graphics

Graphics**

Graphics	Type	Memory	Boost Clock	TGP	Connector	Max Resolution	Key Features	Remark
Intel UHD graphics	Integrated	Shared	-	-	1x HDMI® 1.4b, 1x USB-C®, 1x Thunderbolt™	3840x2160@30Hz(HDMI), 3840x2160@60Hz(USB-C), 3840x2160@60Hz(Thunderbolt)	DirectX® 12	-
Intel Iris Xe Graphics	Integrated	Shared	-	-	1x DP 1.4a, 1x USB-C, 1x Thunderbolt	3840x2160@60Hz(DP), 3840x2160@60Hz(USB-C), 3840x2160@60Hz(Thunderbolt)	DirectX 12	-

Monitor Support

Monitor Support

Supports up to 3 independent displays via onboard ports (i3 models supports HDMI, USB-C, and Thunderbolt; i5 models supports DisplayPort™, USB-C, and Thunderbolt)

Chipset

Chipset

Intel SoC (System on Chip) platform

Memory

Max Memory

- 8GB soldered memory, not upgradable
- 16GB soldered memory, not upgradable

Memory Slots

Memory soldered to systemboard, no slots, dual-channel

Memory Type

DDR4-3200

Memory Protection^[1]

IB-ECC

Notes:

1. IB-ECC needs to be enabled in BIOS

Storage

Storage Support^[1]

- Up to two drives, 2x M.2 2230 SSD
- M.2 2230 SSD up to 1TB each
 - RAID 0/1 support

Storage Type^{***}

Disk Type	Interface	Security
M.2 2230 SSD	PCIe® NVMe®, PCIe 3.0	-
M.2 2230 SSD	PCIe NVMe, PCIe 3.0	Opal

RAID^[2]

RAID 0/1 support

Notes:

1. The storage capacity supported is based on the test results with current Lenovo® storage offerings. The system may support larger storage as the technology develops.
2. RAID preset is available via special bid, limited to the models with Windows 10 IoT Enterprise.

Power Supply

Power Supply

Power	Type	Efficiency	Key Features
65W	Adapter	89%	Autosensing
No power supply	-	-	-

DESIGN

Input Device

Keyboard^{**}

- Lenovo Calliope Keyboard (USB connector), black
- Lenovo Calliope Wireless Keyboard, black
- Lenovo Traditional Keyboard (USB connector), black
- No keyboard

Mouse^{**}

- Lenovo Calliope Mouse (USB connector), black
- Lenovo Fingerprint Mouse (USB connector), black
- No mouse

Mechanical

Dimensions (WxDxH)^[1]

Models	Dimensions
IO box	178 x 88 x 25.6 mm (7.01 x 3.46 x 1.00 inches)
ThinkEdge SE30	179 x 88 x 51.5 mm (7.05 x 3.46 x 2.03 inches)

Weight^[2]

Models	Weight
IO box	Around 0.499 kg (1.10 lbs)
ThinkEdge SE30	Around 1.02 kg (2.25 lbs)

Case Color

Black

IO Box^[3]

- ThinkEdge SE30 IO box: 2x serial (RS232 / RS422 / RS485) and 2x gigabit Ethernet (RJ-45) on front, 1x DIO (4DI / 4DO), USB-C 3.2 Gen 1 (connect to SE30), and DC-in connector (9V - 36V) on rear
- No IO box

Mounting**

- VESA mount bracket kit with adapter holder, supports VESA mount 75mm and 100mm
- VESA mount bracket kit, supports VESA mount 75mm and 100mm
- DIN rail mount bracket kit
- Z hook
- None

Notes:

1. The system dimensions may vary depending on configurations.
2. The system weight is approximate and based on results in Lenovo lab, which varies depending on the source of component, variance of the distribution of each component, and manufacturing process. It may not be the exact weight for each specific model.
3. For more details, please go to <https://pcsupport.lenovo.com>

CONNECTIVITY**Network****Ethernet**

1x gigabit Ethernet (Realtek® RTL8111KI-CG) and 1x 2.5 gigabit Ethernet (Intel I225-IT), 2x RJ-45, supports Wake-on-LAN

WLAN + Bluetooth®[1]**

- Intel Wireless-AC 9260, 802.11ac Dual Band 2x2 Wi-Fi® + Bluetooth 5.0, Intel vPro® technology support, M.2 card
- Intel Wireless-AC 9260, 802.11ac Dual Band 2x2 Wi-Fi + Bluetooth 5.0, M.2 card
- No WLAN and Bluetooth

WWAN**

- Quectel EM160R-GL, Qualcomm® Snapdragon™ X24 LTE Modem, CAT16, M.2 card
- Qualcomm Snapdragon X55 5G Modem-RF System, Sub-6 GHz, M.2 card
- No support

Notes:

1. Bluetooth 5.2 is hardware ready but may run at a lower version due to OS limitations.

Ports^[1]**Front Ports**

- 2x USB 3.2 Gen 2
- 1x USB-C 3.2 Gen 2 (support data transfer and display)
- 1x headphone / microphone combo jack (3.5mm)
- 2x serial (RS232 / RS422 / RS485, BIOS selectable)

Optional Front Ports***

- 2x gigabit Ethernet (RJ-45) on SE30 IO box
- 2x serial (RS232 / RS422 / RS485, SDK selectable) on SE30 IO box

Rear Ports^[2]

- 1x Thunderbolt 4 / USB4® 40Gbps (support data transfer, Power Delivery 5V@3A, and display)
- 1x HDMI 1.4b (for i3 models)
- 1x DisplayPort 1.4a (for i5 models)
- 1x USB 3.2 Gen 2
- 2x Ethernet (RJ-45)
- 1x power connector

Optional Rear Ports***

- 1x USB-C 3.2 Gen 1 on SE30 IO box, connect to SE30
- 1x DC-in 3pin Phoenix connector on SE30 IO box
- 1x DIO (4DI / 4DO) on SE30 IO box

Notes:

1. The transfer speed of following ports will vary and, depending on many factors, such as the processing speed of the host device, file attributes and other factors related to system configuration and your operating environment, will be slower than theoretical speed.
USB 2.0: 480 Mbit/s;
USB 3.2 Gen 1 (SuperSpeed USB 5Gbps, formerly USB 3.0 / USB 3.1 Gen 1): 5 Gbit/s;
USB 3.2 Gen 2 (SuperSpeed USB 10Gbps, formerly USB 3.1 Gen 2): 10 Gbit/s;
USB 3.2 Gen 2x2 (SuperSpeed USB 20Gbps): 20 Gbit/s;
Thunderbolt 3/4: 40 Gbit/s

2. If IO box gets power supply from ThinkEdge SE30, need to connect USB-C (on IO box) with Thunderbolt 4 port (on SE30)

Monitor Cable

Monitor Cable***

- USB-C to DP dongle
- USB-C to HDMI dongle
- USB-C to VGA dongle
- DP to VGA dongle
- DP to Dual DP (MST) dongle
- DP to Dual DP (SST) dongle
- DP to HDMI 1.4 dongle
- No monitor cable

SECURITY & PRIVACY

Security

Security Chip

Discrete TPM 2.0, TCG certified

Physical Locks

Kensington® Security Slot™, 3 x 7 mm

Chassis Intrusion Switch

Chassis intrusion switch

BIOS Security

- Self-healing BIOS
- Self-healing BIOS (EC-based)

MANAGEABILITY

System Management

System Management

- Intel vPro with Intel AMT 15
- Non-vPro

SERVICE

Warranty^[1]

Base Warranty**

- 1-year courier or carry-in service
- 1-year limited onsite service
- 3-year limited onsite service
- No base warranty

Notes:

1. The warranty upgrades may be bundled with some models, please check the "Included upgrade" column in the specific model's configurations. For more service extensions, please go to <https://smartfind.lenovo.com/>. To learn more details of warranty policy, please access <https://pcsupport.lenovo.com/warranty>.

ENVIRONMENTAL

Operating Environment^[1]

Temperature

- Operating: IEC60068-2-1 Test A: Cold, IEC 60068-2-2 Test B: Dry heat, -20°C (-4°F) to 60°C (140°F) with 0.7 m/s air flow
- Storage: IEC60068-2-1 Test A: Cold, IEC 60068-2-2 Test B: Dry heat, -40°C (-40°F) to 85°C (185°F)

Humidity

- Relative humidity storage: IEC 60068-2-66 Damp heat, steady state 90%@60°C

- Relative humidity operating: IEC 60068-2-66 Damp heat, steady state 95%@40°C non-condensing

Shock Protection

IEC 60068-2-27, shock, operating, 30G / 11ms, half sine

Vibration Protection

IEC 60068-2-64, Vibration, Operating, 3Grms, random, 5 ~ 500Hz, 1hr/axis

Notes:

1. The temperature spec is not applicable for hardware accessories.

CERTIFICATIONS

Green Certifications

Green Certifications

- ErP Lot 6/26
- Low Halogen
- RoHS compliant
- REACH
- PCF
- TED (ECO-declaration)
- WEEE

Other Certifications

EMC

- EMC CE / FCC Class B
- BSMI
- CCC

Safety

- UL(ETL)
- BSMI
- CB
- CCC

- Feature with ** means that only one offering listed under the feature is configured on selected models.
- Feature with *** means that one or more offerings listed under the feature could be configured on selected models.
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